



**PATENT** 

**RESPONSE UNDER 37 C.F.R. 1.116 - EXPEDITED PROCEDURE - EXAMINING GROUP 3728** 

Attorney Docket No. 5649-885

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Shim et al. Serial No.: 09/903,070

Commissioner for Patents Washington, DC 20231

Filed: July 11, 2001 For:

METHODS OF PACKAGING SEMICONDUCTOR WAFERS BY MOLDING A

SEMICONDUCTOR WAFERS

Group Art Unit: 3728 Examiner: Anthony D. Stashick

Confirmation No.: 9380

PACKING BAG ABOUT A CARRYING DEVICE THAT CONTAINS THE

Date: April 14, 2003

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APR 2 3 2003

**TECHNOLOGY CENTER R3700** 

AMENDMENT AFTER FINAL **PURSUANT TO 37 C.F.R. § 1.116** 

Sir:

**BOX AF** 

Applicant provides the present Amendment to address the issues raised in the Final Official Action mailed February 25, 2003. Applicant provides the present Amendment pursuant to the Revised Amendment Format instituted for the prototype Electronic File Wrapper program described in 1265 Off. Gaz. Pat. Office 87 (Dec. 17, 2002) and that has been expanded to include all Technology Centers and amendments to the specification and drawings. Thus, the provisions of 37 C.F.R. 1.121(a), (b), (c) and (d) are waived for the present Amendment.